

SN74LVTH543-EP

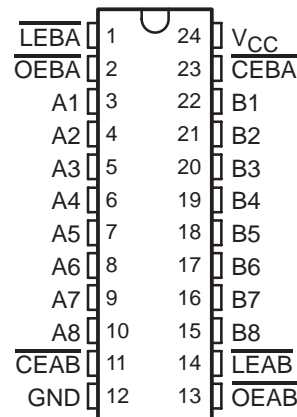
3.3-V ABT OCTAL REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

SCBS772 – NOVEMBER 2003

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

PW PACKAGE
(TOP VIEW)



description/ordering information

This octal transceiver is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTH543 contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (\overline{LEAB} or \overline{LEBA}) and output-enable (\overline{OEAB} or \overline{OEBA}) inputs are provided for each register, to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be low to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – PW	Tape and reel	SN74LVTH543IPWREP	LH543EP

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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description/ordering information (continued)

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

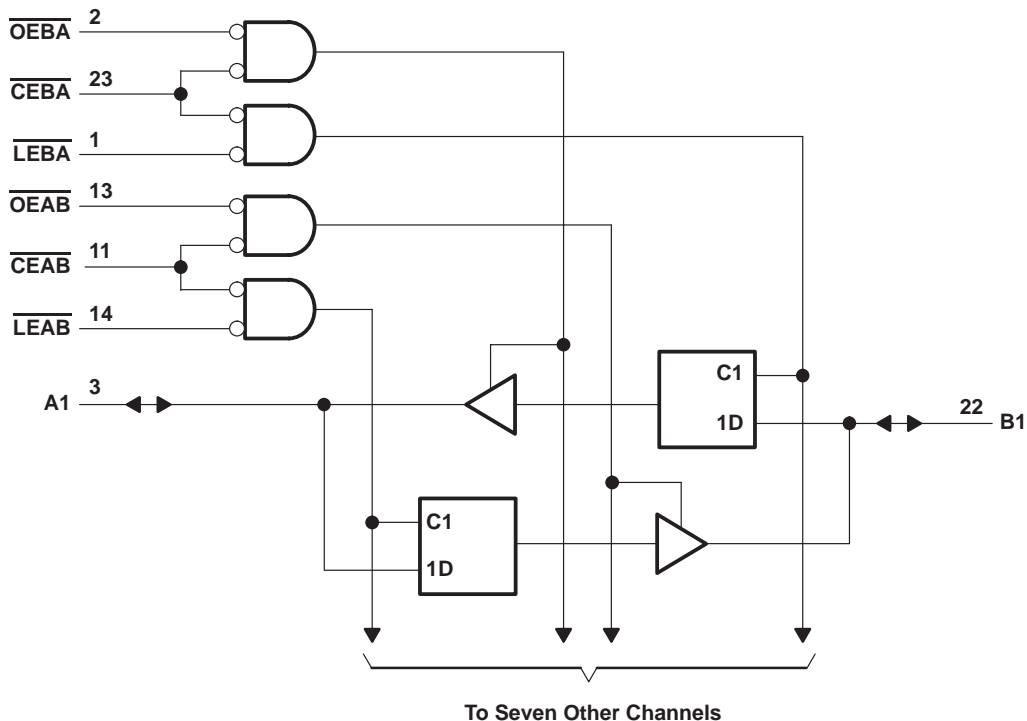
FUNCTION TABLE†

INPUTS				OUTPUT
\overline{CEAB}	\overline{LEAB}	\overline{OEAB}	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0^\ddagger
L	L	L	L	L
L	L	L	H	H

† A-to-B data flow is shown; B-to-A flow control is the same, except that it uses \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} .

‡ Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O	128 mA
Current into any output in the high state, I_O (see Note 2)	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3)	88°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage		5.5	V
I_{OH}	High-level output current		–32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
			10	ns/V
			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		μs/V
T_A	Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 2.7 V, I _I = -18 mA			-1.2	V
V _{OH}		V _{CC} = 2.7 V to 3.6 V, I _{OH} = -100 μA	V _{CC} -0.2			V
		V _{CC} = 2.7 V, I _{OH} = -8 mA	2.4			
		V _{CC} = 3 V, I _{OH} = -32 mA	2			
V _{OL}		V _{CC} = 2.7 V	I _{OL} = 100 μA		0.2	V
			I _{OL} = 24 mA		0.5	
		V _{CC} = 3 V	I _{OL} = 16 mA		0.4	
			I _{OL} = 32 mA		0.5	
			I _{OL} = 64 mA		0.55	
I _I		Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND		±1	μA
			V _{CC} = 0 or 3.6 V, V _I = 5.5 V		10	
		A or B ports‡	V _{CC} = 3.6 V, V _I = 5.5 V		20	
			V _{CC} = 3.6 V, V _I = V _{CC}		1	
		V _{CC} = 3.6 V, V _I = 0		-5		
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V			±100	μA
I _I (hold)		A or B ports	V _{CC} = 3 V, V _I = 0.8 V		75	μA
			V _{CC} = 3 V, V _I = 2 V		-75	
		V _{CC} = 3.6 V§		V _I = 0 to 3.6 V		
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 to 3 V, \overline{OE} = don't care			±100	μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 to 3 V, \overline{OE} = don't care			±100	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		0.19	mA
			Outputs low		5	
			Outputs disabled		0.19	
ΔI _{CC} ¶		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND			0.2	mA
C _i		V _I = 3 V or 0			4	pF
C _{io}		V _O = 3 V or 0			9	pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ Unused terminals are at V_{CC} or GND.

§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
t _w	Pulse duration,	$\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ low	3.3		3.3		ns
t _{su}	Setup time	A or B before $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}\uparrow$	Data high	0.4	0.4	ns	
			Data low	1	1.5		
		A or B before $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}\uparrow$	Data high	0.2	0.2		
			Data low	0.7	1.2		
t _h	Hold time	A or B after $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}\uparrow$	Data high	1.5	0.6	ns	
			Data low	1.3	1.5		
		A or B after $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}\uparrow$	Data high	1.6	0.5		
			Data low	1.4	1.6		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1.3	2.5	3.7	4.3		ns
t _{PHL}			1.3	2.5	3.7	4.3		
t _{PLH}	$\overline{\text{LE}}$	A or B	1.3	2.9	4.7	5.9		ns
t _{PHL}			1.3	2.9	4.7	5.9		
t _{PZH}	$\overline{\text{OE}}$	A or B	1.1	2.9	4.9	6.2		ns
t _{PZL}			1.1	3.2	4.9	6.2		
t _{PHZ}	$\overline{\text{OE}}$	A or B	2	3.4	5.3	5.9		ns
t _{PLZ}			2	3.7	5.3	5.9		
t _{PZH}	$\overline{\text{CE}}$	A or B	1.3	3.2	5.3	6.8		ns
t _{PZL}			1.3	3.5	5.3	6.8		
t _{PHZ}	$\overline{\text{CE}}$	A or B	2.3	3.8	5.4	5.9		ns
t _{PLZ}			2.3	3.9	5.4	5.6		

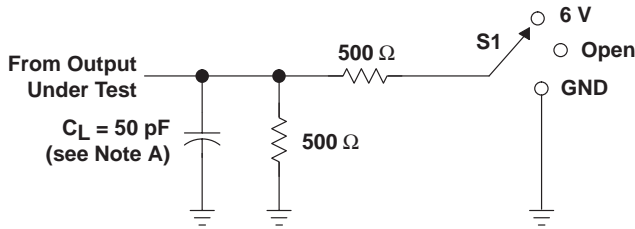
† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

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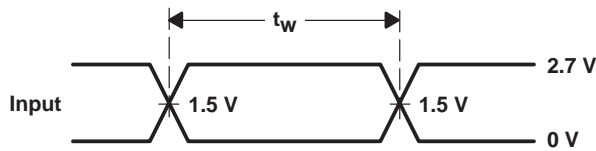
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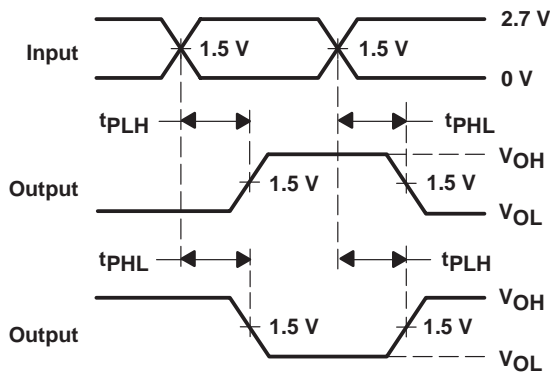
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

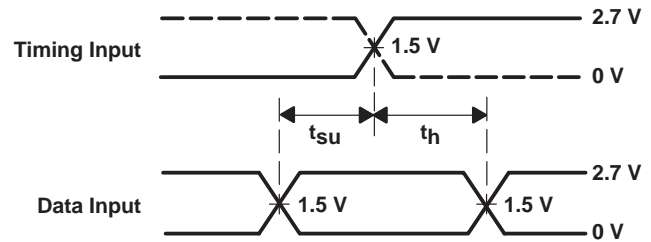


VOLTAGE WAVEFORMS
PULSE DURATION

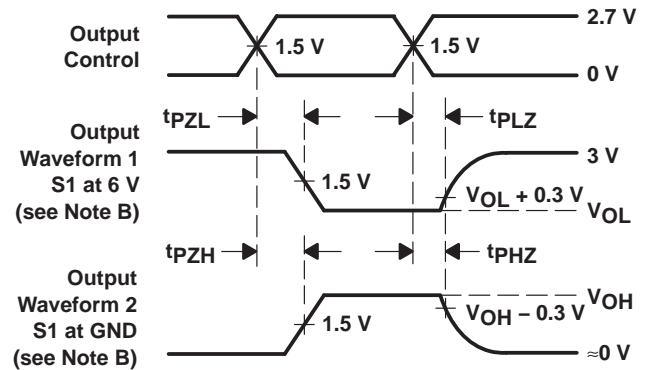


VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVTH543IPWREP	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04677-01XE	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVTH543-EP :

- Catalog: [SN74LVTH543](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH543IPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH543IPWREP	TSSOP	PW	24	2000	346.0	346.0	33.0

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